

Sipeed M1W Datasheet V1.12



Key Features:

- CPU: RISC-V Dual Core 64bit, with FPU, 400Mhz-500Mhz, Neural network processor
- Image Recognition: QVGA@60FPS/VGA@30FPS
- Voice Recognition: up to 8 microphones
- Deep learning framework: TensorFlow/Keras/Darknet
- Peripheral: FPIOA、UART、GPIO、SPI、I²C、I²S、WDT、TIMER、RTC etc.
- Wireless Function: Support 2.4G 802.11.b/g/n

Sipeed Technology www.sipeed.com



UPDATE		
V1.0	2018/3/6 Published original document	
V1.1	Add FCC warning	
V1.11(In this version, the M1W have been FCC certified)	Update the picture of home page Update the pin table Update the pin map Updated the laser engraving information of the shield case(Add FCC ID) Add the SPI connections between K210 and ESP8285(Only valid in this and future versions)	
V1.12	2021/10/11 Fixed PIN MAP picture; Add precautions	



	SPECIFICATION
CPU : RISC-V Dual Core 64bit, 400Mh adjustable	Powerful dual-core 64-bit open architecture-based processor with rich community resources
FPU Specifications	IEEE754-2008 compliant high-performance pipelined FPU
Debugging Support	High-speed UART and JTAG interface for debugging
Neural Network Processor (KPU)	Supports the fixed-point model that the mainstream training framework trains according to specific restriction rules There is no direct limit on the number of network layers, and each layer of convolutional neural network parameters can be configured separately, including the number of input and output channels, and the input and output line width and column height Support for 1x1 and 3x3 convolution kernels Support for any form of activation function The maximum supported neural network parameter size for real-time work is 5MiB to 5.9MiB The maximum supported network parameter size when working in non-real time is (flash size - software size)
Audio Processor (APU)	 Up to 8 channels of audio input data, ie 4 stereo channels Simultaneous scanning pre-processing and beamforming for sound sources in up to 16 directions Supports one active voice stream output 16-bit wide internal audio signal processing Support for 12-bit, 16-bit, 24-bit, and 32-bit input data widths • Multi-channel direct raw signal output Up to 192kHz sample rate Built-in FFT unit supports 512-point FFT of audio data Uses system DMAC to store output data in system memory
Static Random-Access Memory (SRAM)	The SRAM is split into two parts, 6MiB of on-chip general-purpose SRAM memory and 2MiB of on-chip Al SRAM memory, for a total of 8MiB
Field Programmable IO Array (FPIOA/IOMUX)	FPIOA allows users to map 255 internal functions to 48 free IOs on the chip
Digital Video Port (DVP)	Maximum frame size 640x480
FFT Accelerator	The FFT accelerator is a hardware implementation of the Fast Fourier Transform (FFT)



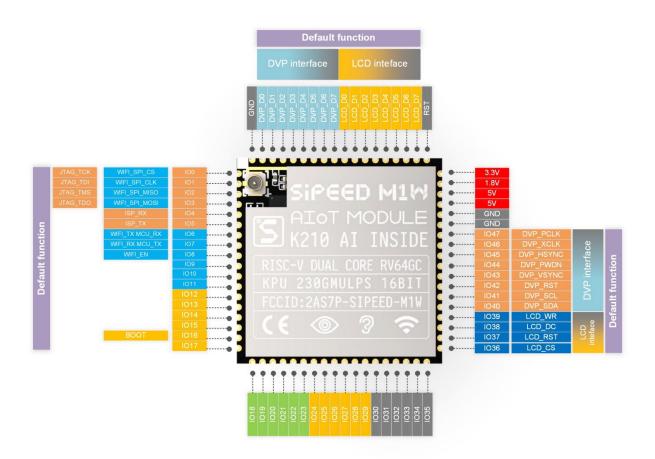
SOFTWARE FEATURES		
FreeRtos & Standard SDK	FreeRtos & Standard SDK	
MicroPython Support	MicroPython Support	
Machine vision	Machine vision	
Machine hearing	Machine hearing	

HARDWARE FEATURES		
Supply voltage of external power supply	5.0V ±0.2V	
Supply current of external power supply	> 600mA @ 5V	
Temperature rise	<30K	
Range of working temperature	-30°C ~ 85°C	

RF FEATURES			
MCU : ESP8285	Tensilica L106 32-bit MCU		
Wireless Standard	802.11 b/g/n		
Frequency Range	2400Mhz - 2483.5Mhz		
TX Power (Conduction test)	802.11.b: +15dBm(±2dBm) 802.11.g: +10dBm(±2dBm)(54Mbps) 802.11.n: +10dBm(±2dBm) (65Mbps)		
Antenna Connector	IPEX 3.0x3.0mm		
Wi-Fi mode	Station/SoftAP/SoftAP+Station		
The connection between K210 and ESP8285	SPI and UART Please read the schema of M1w_V1.11 for the specification (dl.sipeed.com)		

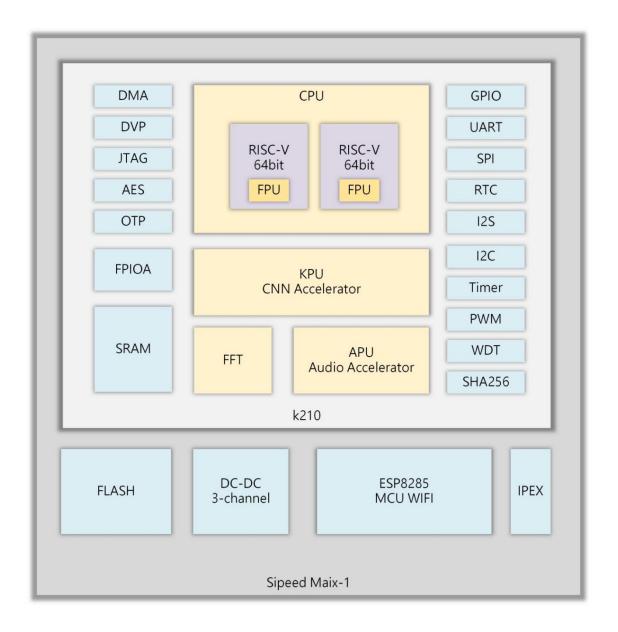


M1W PIN MAP





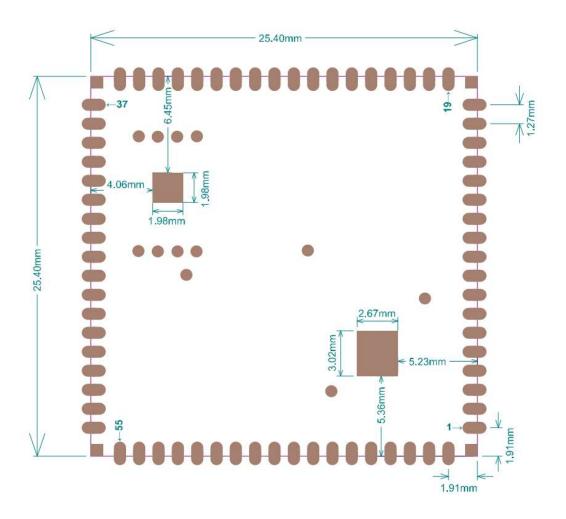
M1W BLOCK DIAGRAM





SIZE		
Length	25.4mm	
Width	25.4mm	
Height	3.3mm	

Sipeed M1W PIN ASSIGNMENT



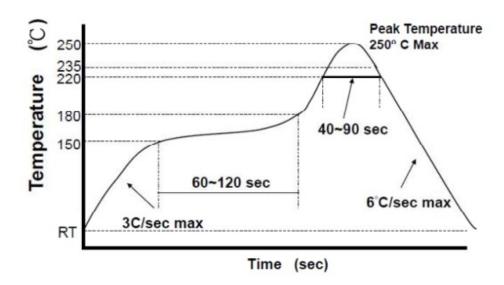


#	PIN	#	PIN	#	PIN	#	PIN
1	JTAG_TCK	19	MIC_BCK	37	LCD_CS	55	RST
2	JTAG_TDI	20	MIC_WS	38	LCD_RST	56	LCD_D7
3	JTAG_TMS	21	MIC_DAT3	39	LCD_DC	57	LCD_D6
4	JTAG_TDO	22	MIC_DAT2	40	LCD_WR	58	LCD_D5
5	ISP_RX	23	MIC_DAT1	41	DVP_SDA	59	LCD_D4
6	ISP_TX	24	MIC_DAT0	42	DVP_SCL	60	LCD_D3
7	WIFI_TX MCU_RX	25	MIC_LED_DAT	43	DVP_RST	61	LCD_D2
8	WIFI_RX MCU_TX	26	SPI0_CS1	44	DVP_VSYNC	62	LCD_D1
9	WIFI_EN	27	SPI0_MISO	45	DVP_PWDN	63	LCD_D0
10	109	28	SPI0_SCLK	46	DVP_HSYNC	64	DVP_D7
11	IO10	29	SPI0_MOSI	47	DVP_XCLK	65	DVP_D6
12	1011	30	SPI0_CS0	48	DVP_PCLK	66	DVP_D5
13	LED_G	31	MIC0_WS	49	GND	67	DVP_D4
14	LED_B	32	MIC0_DATA	50	GND	68	DVP_D3
15	LED_R	33	MIC0_BCK	51	5V	69	DVP_D2
16	1015	34	12S_WS	52	5V	70	DVP_D1
17	BOOT KEY0	35	I2S_DA	53	1V8	71	DVP_D0
18	IO17	36	I2S_BCK	54	3V3	72	GND

Note: The small square pad in the lower right corner of the dimension drawing is WIFI_GPIO0, and the other three corners are GND.



REFLOW PROFILE GUIDELINE



Mat	ters needing attention
	At startup, BOOT pin is used to select one of two boot
	options:
Boot mode selection	• Boot from main flash memory (Set BOOT pin 3.3V)(Float or
	pull up to 3.3V)
	• Enter ISP download mode (Set BOOT pin 0V)
RST pin	Vrst range : 0 to 1.8V ; Active low ; Do not let the voltage of
	RST pin be greater than 1.8V
	It is recommended to connect the pad on the bottom of the
Thermal design	module to a large piece of copper on the bottom plate to help
	heat dissipation
	1. All IO ports and power pins used need to be equipped with
Electrostatic protection	ESD diodes
	2. All IO ports used need a resistance between 100Ω -1k Ω in
	series
Precautions for PCB design using this	https://bbs.sipeed.com/thread/62
module	Tittps://bbs.sipeed.com/tillead/02



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